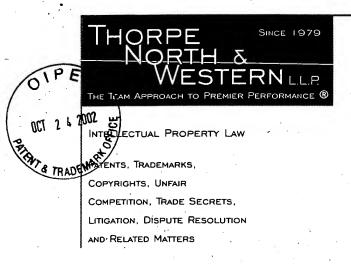
Docket No. T5100CIP2

Vaughn W. North



SALT LAKE AREA OFFICE
8180 SOUTH 700 EAST, SUITE 200
SANDY, UTAH 84070-0562
801.566.6633
801.566.0750 FAX
PATLAW@TNW.COM
WWW.TNW.COM

U.S. MAILING ADDRESS P.O. BOX 1219 SANDY, UTAH 84091-1219

LAS VEGAS AREA OFFICE
OF COUNSEL: NEIL J. BELLER †
7408 WEST SAHARA
LAS VEGAS, NEVADA 89 1 1 7
702.368.7767
† ADMITTED IN NEVADA

VAUGHN W. NORTH
M. WAYNE WESTERN
CLIFTON W. THOMPSON
GARRON M. HOBSON
PETER M. DE JONGE
STEVE M. PERRY
WEILI CHENG, PH.D.
DAVID R. MCKINNEY, PE.
GARY P. OAKESON
DAVID W. OSBORNE
KEITH HARGROVE
DAVID L. STOTT
JASON R. JONES
REGISTERED PATENT ATTORNEYS

ERIK S. ERICKSEN, M.S. REGISTERED PATENT AGENT

TODD B. ALDER, PH.D. JONATHAN M. BENNS, PH.D. TECHNICAL CONSULTANTS

> CALVIN E. THORPE (1938-1999)

October 21, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents Washington, D.C. 20231

OCT 2 5 2002

TECHNOLOGY CENTER RE700

Sir:

Transmitted herewith for filing and pursuant to 37 C.F.R. §§ 1.56 and 1.97 is an Information Disclosure Statement.

Enclosed also are the following designated documents, as required under 37 C.F.R. §§ 1.97 and 1.98:

- X Form PTO-1449 list of references submitted for consideration.
- \underline{X} Legible copies of the listed references or their relevant portions.
- All English translations of each non-English reference, if any, within the possession, custody, control or availability of anyone designated in 37 C.F.R. § 1.56(c) (see 37 C.F.R. § 1.98(c)).

The following are included within the Information Disclosure Statement if applicable and as required under 37 C.F.R. § 1.98:

- X Concise explanation of relevance of each reference not in English and unaccompanied by an English translation.
- ___ Statement that certain listed references not enclosed are substantially cumulative of an enclosed reference.

| <u>—</u> : · , | Statement that certain listed references not enclosed were submitted to the Office in the identified prior application an earlier filing date under 35 U.S.C. § 120. | |
|----------------|--|---------------------|
| | er to secure consideration of the items designated above, required, is also enclosed: | one or more of the |
| . | Statement under 37 C.F.R. § 1.97(e)(1) or (2). | |
| | Check No in the amount of \$ (amount in § 1.17(p submission fee set forth in 37 C.F.R. § 1.17(p). |)) constituting the |

In the event that 37 C.F.R. § 1.97(c) applies and the Examiner is not satisfied that the Statement meets the requirements of 37 C.F.R. § 1.97(e), or in any other event remediable by a fee, please credit any over payment or charge any additional fees to Deposit Account No. 20-0100 of the undersigned.

Dated this 2/3+ day of October, 2002.

Respectfully submitted,

ms, of annostration

M. Wayne Western Registration No. 22,788 Attorney for Applicant

THORPE NORTH & WESTERN, L.L.P.

Customer No. 20,551 P.O. Box 1219 Sandy, UT 84091-1219 Telephone (801) 566-6633

MWW/DWO/vm
H:\FILES\T5000\T5100\CIP2\ids transmittal.frm



PATENT APPLICATION DOCKET NO. T5100.CIP2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

Chien-Min Sung

SERIAL NO.:

09/935,204

FILED:

08/22/2001

FOR:

BRAZED DIAMOND TOOLS AND

METHODS FOR MAKING

ART UNIT:

3723

EXAMINER:

DOCKET NO.:

T5100CIP2

CERTIFICATE OF DEPOSIT UNDER 37 C.F.R. 1.8

I hereby certify that this paper or fee is being deposited with the United States Postal Service under 37 C.F.R. § 1.8 on the date indicated above and is addressed to: Box DD, Assistant Commissioner for Patents, Washington, DC 20231.

Signature

Dated Oct.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97

Box: DD

Assistant Commissioner of Patents

Washington, D.C. 20231

RECEIVED AND A 2002

TECHNOLOGY CENTER 1...700

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). Applicant respectfully submits that this Information Disclosure Statement is filed pursuant to:

X 37 C.F.R. § 1.97 (b)(1) or (3), within three months of the filing date of the application, or before a first office action on the merits, whichever occurs last;

_____ 37 C.F.R. § 1.97 (c), after a first office action on the merits, but before a Final Office Action or a Notice of Allowance, whichever occurs first, and is accompanied by either 1) a statement in accordance with 37 C.F.R. § 1.97(e), or 2) the fee set forth in§1.17(p); or ______ 37 C.F.R. § 1.97 (d), after a Final Office Action or Notice of Allowance, whichever occurs first, but on or before payment of the issue fee, and is accompanied by both 1) a statement in accordance with 37 C.F.R. § 1.97(e), and 2) the fee set forth in§1.17(p).

While no representation is made that any of these references may be "prior art" within the meaning of that term in accordance with 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record believes that the references listed, together with any other references which may have been previously submitted or listed, are the closest to the claimed invention (taken in its entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

In accordance with 37 C.F.R. §§ 1.97 and 1.98, a copy of each listed reference (or relevant portion thereof) which was not previously submitted to, or cited by, the Patent Office is also enclosed.

For all listed references that are not either in the English language, or accompanied by a translation into English, a concise explanation of relevance as required under 37 C.F.R. § 1.98(a)(3) is enclosed attached to each.

Please charge any additional fees or credit any overpayment to Deposit Account

No. 20-0100.

DATED this 2/5 day of October, 2002.

Respectfully submitted,

M. Wayne Western Attorney for Applicant

Registration No. 22,788

202 Waymort

THORPE NORTH & WESTERN, L.L.P.

Customer No. 20,551

P.O. Box 1219

Sandy, Utah 84091-1219

Telephone (801) 566-6633

MWW/DWO/vm

Enclosures

[H:\FILES\T5000\T5100\T5100.CIP2\supp ids.wpd]



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

Chien-Min Sung

SERIAL NO:

09/935,204

FILED:

August 22, 2001

FOR:

BRAZED DIAMOND TOOLS AND

METHODS FOR MAKING THE

SAME

ART UNIT:

3723

EXAMINER:

DOCKET NO:

T5100CIP2

CERTIFICATE OF DEPOSIT UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail, postage prepaid, under 37 C.F.R. §1.8 on the date indicated below and is addressed to Assistant Commissioner of Patents, Washington, D.C. 20231.

<u>Uct.</u> 2

STATEMENT OF RELEVANCE UNDER 37 C.F.R. §1:98(a)(3)

Assistant Commissioner for Patents Washington, D.C. 20231

OCT 2 5 2002

TECHNOLOGY CENTER R3700

Sir/Madam:

Please find, pursuant to 37 C.F.R. §1.98(a)(3), a concise Statement of Relevance for JP10128654A, JP10180618A, JP11048122A and JP11077536A.

JP10128654A:

This patent contains an invention which utilizes a diamond dresser to groom an abrasive cloth used for polishing purposes in a CMP device. Particularly, the diamond dresser includes a material which is capable of mechanically removing a diamond abrasive grain from the abrasive cloth after it has become dislodged from the diamond dresser. Additionally, the abrasive cloth

includes a dimple or other wear indicator which is used to signify an amount of wear which has occurred to the abrasive cloth.

This patent is relevant to the invention of the present application only in that it discloses a CMP pad dresser which utilizes a plurality of diamond grits or abrasive grains, for dressing a CMP pad.

JP10180618A:

This patent discloses a polishing pad having different areas of roughness to correspond to areas of varying thicknesses on a semiconductor substrate material which is to be polished flat. The degree of roughness corresponds to the thickness, or amount of material to be removed, from the semiconductor substrate. Therefore, the rougher areas of the pad remove material from the semiconductor substrate at a greater rate than those areas which are less rough. In this manner, a uniform and flat surface may be achieved in a more efficient manner. Additionally, diamond grinding wheels having a variety of degrees of hardness are used in order to form the varying degrees of roughness on the pad surface.

This patent relates to the invention of the present application only in that a diamond wheel is brought in contact to the surface of a polishing, or material removing, pad.

JP11048122A:

This patent discloses a CMP polishing pad for polishing semiconductor wafers. The CMP pad is groomed or dressed with two CMP pad dressers. The first CMP pad dresser has a diamond particle containing surface which is used to create a uniform polishing pad surface. The polishing pad then grinds upon the semiconductor wafer, and is next dressed by a second dressing tool

which has a cylindrical brush for rejuvinating the polishing pad. Finally, a supply nozzle is used to restore the abrasives contained in the pad fibers.

This patent relates to the invention of the present application only in that it uses a CMP pad dresser which contains diamond particles for dressing CMP pad. However, the use of the diamond CMP pad dresser in this patent seems to be focused on achieving a uniform polishing pad surface rather than restoring the disposition of pad fibers after they have performed a polishing step.

JP11077536A:

This patent discloses a CMP conditioner with diamond abrasive grains which are fixed by an electroplating method to a plated layer. The electroplating is then coated with a nitric acid resistant plating or synthetic resin so as to allow the chips of the diamond abrasive grains to project above the resin layer.

This patent is relevant to the invention of the present application only in that it discloses a diamond particle containing CMP pad dresser. Further, it is relevant in that it discloses a means for reducing diamond particle displacement due to chemical attack. However, in this instance, a resin layer is employed as the mechanism by which the chemical attack is prevented.

The above statements are believed to fully comply with the requirements of 37 C.F.R.§1.98(a)(3). The Examiner is invited to contact the applicant in the event that there is any deficiency found therein.

DATED this 2 13 day of October, 2002.

Respectfully submitted,

on. Wayn or bate

M. Wayne Western

Attorney for Applicant Registration No. 22,788

THORPE NORTH & WESTERN, L.L.P. P.O. Box 1219 Sandy, Utah 84091-1219

Telephone (801) 566-6633

MWW/DWO/vm

H:\FILES\T5000\T5100\T5100.CIP3\stmtofrelevance.wpd